



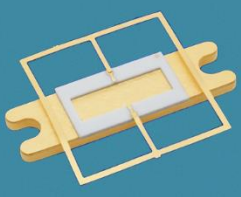
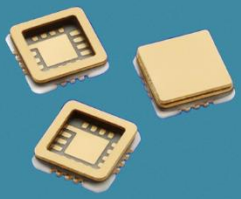
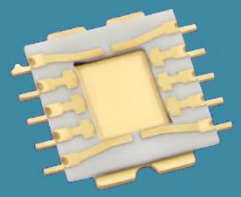
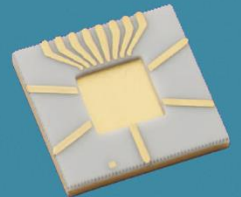
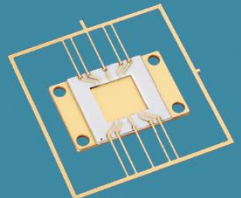
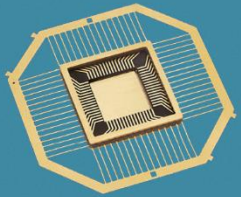
S T R A T E D G E

High-Performance Packaging Solutions

High Frequency

High Speed

High Power



StratEdge designs and manufactures high-performance semiconductor packages and provides chip assembly and test services. We specialize in packages for high-frequency, very high power, extremely demanding gallium arsenide (GaAs) and gallium nitride (GaN) devices and have a complete line of post-fired and molded ceramic semiconductor packages that operate from DC to 63+ GHz. Our patented electrical transition designs give StratEdge packages exceptionally low electrical losses, even at 63+ GHz. Markets served include telecom, mixed signal, VSAT, broadband wireless, satellite, military, test and measurement, automotive, down-hole, and MEMS. StratEdge is an ISO 9001:2015 facility, with all manufacturing done at our San Diego, California headquarters.

MC Series

- Fully Hermetic, supplied with metal lid with AuSn preform
- High thermal conductivity bases available
- Custom designs available for low NRE

LPA

- Low loss from DC to 23 GHz
- Supplied with cup-shaped lid with epoxy preform

SE50

- Low loss from DC to 63 GHz
- High thermal conductivity Cu-composite bases
- Supplied with cup-shaped lid with epoxy preform
- Wire or ribbon bonded directly to board

SMX/SMK

- Low-cost surface mount microwave packages
- High thermal conductivity Cu-composite bases
- Excellent electrical properties through K band
- Supplied with cup-shaped lid with epoxy preform

Ceramic QFN

- High frequency performance with air cavity configuration
- QFN outlines from 3x3mm to 8x8mm
- Low loss from DC to 43GHz
- Metal lid with AuSn solder preform or ceramic lid with b-stage epoxy options
- Multiple base options available

LL Leaded Laminate Series

- Packaging for high-power Gallium Nitride (GaN) products
- Enhanced thermal dissipation of GaN devices
- Copper:Molybdenum:Copper (CMC 1:3:1) laminates for eutectic solder attachment
- Matched thermal expansion of die
- Enables solder die bond line thickness less than 0.00025"



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